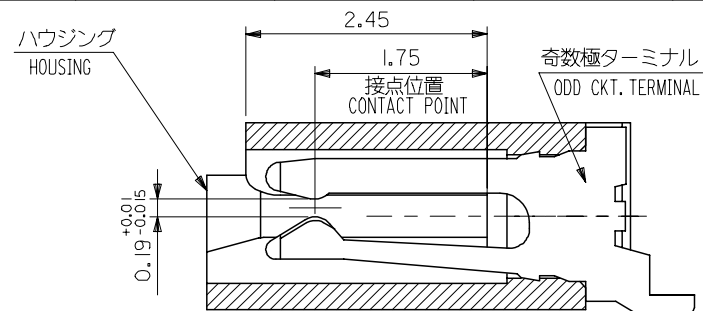
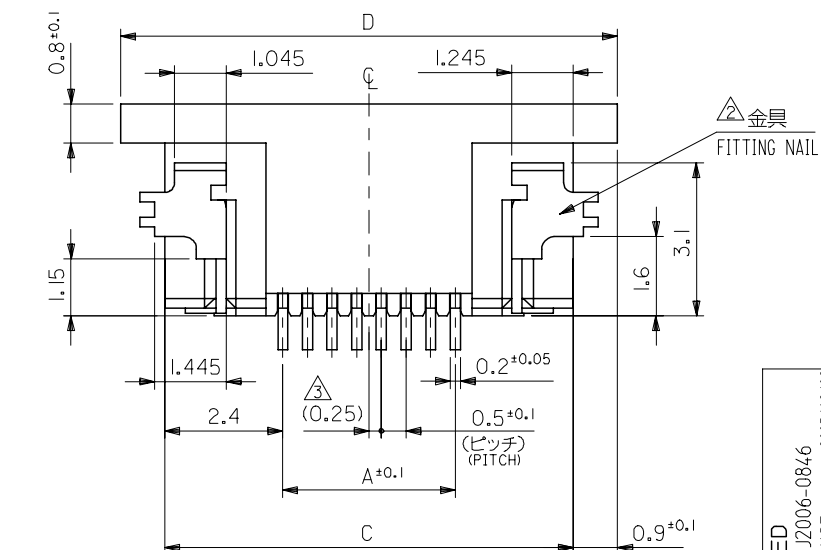
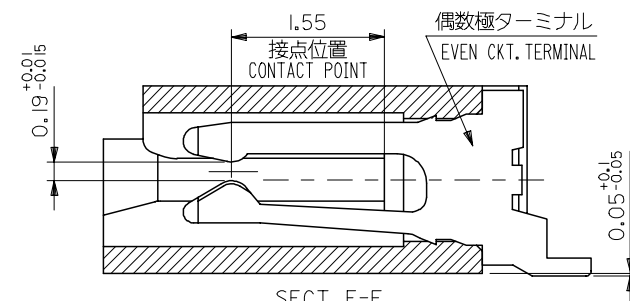




SECT. M-M
SCALE 20:1



SECT. F-F
SCALE 20:1

注記(NOTES)

7. 使用材料 (MATERIAL)
- ターミナル (TERMINAL): リン青銅、全メッキ (接点部): 0.1マイクロメートル以上
銅メッキ (テール部): 1.0マイクロメートル以上
ニッケル下地: 1.0マイクロメートル以上
- 本製品は、封孔処理品である。
- PHOSPHOR BRONZE 10-2, GOLD (CONTACT): 0.1 MICROMETER MINIMUM
TIN (TAIL) PLATING: 1.0 MICROMETER MINIMUM
OVER NICKEL: 1.0 MICROMETER MINIMUM
- THIS PRODUCT IS SEALING DISPOSITION.
- ハウジング (HOUSING): 46ナイロン (46NYLON), UL94V-0
- 金具 (FITTING NAIL): リン青銅、銅メッキ: 1.0マイクロメートル以上
ニッケル下地: 1.0マイクロメートル以上
- PHOSPHOR BRONZE 10-2, TIN PLATING: 1.0 MICROMETER MINIMUM
OVER NICKEL: 1.0 MICROMETER MINIMUM

△ パターン剥離止め用金具。(FITTING NAIL FOR PREVENTION OF PEELING OFF PCB,PATTERN.)

③ 偶数極に適用。(TO BE APPLIED ONLY WHEN ALL CKTS. ARE EVEN.)

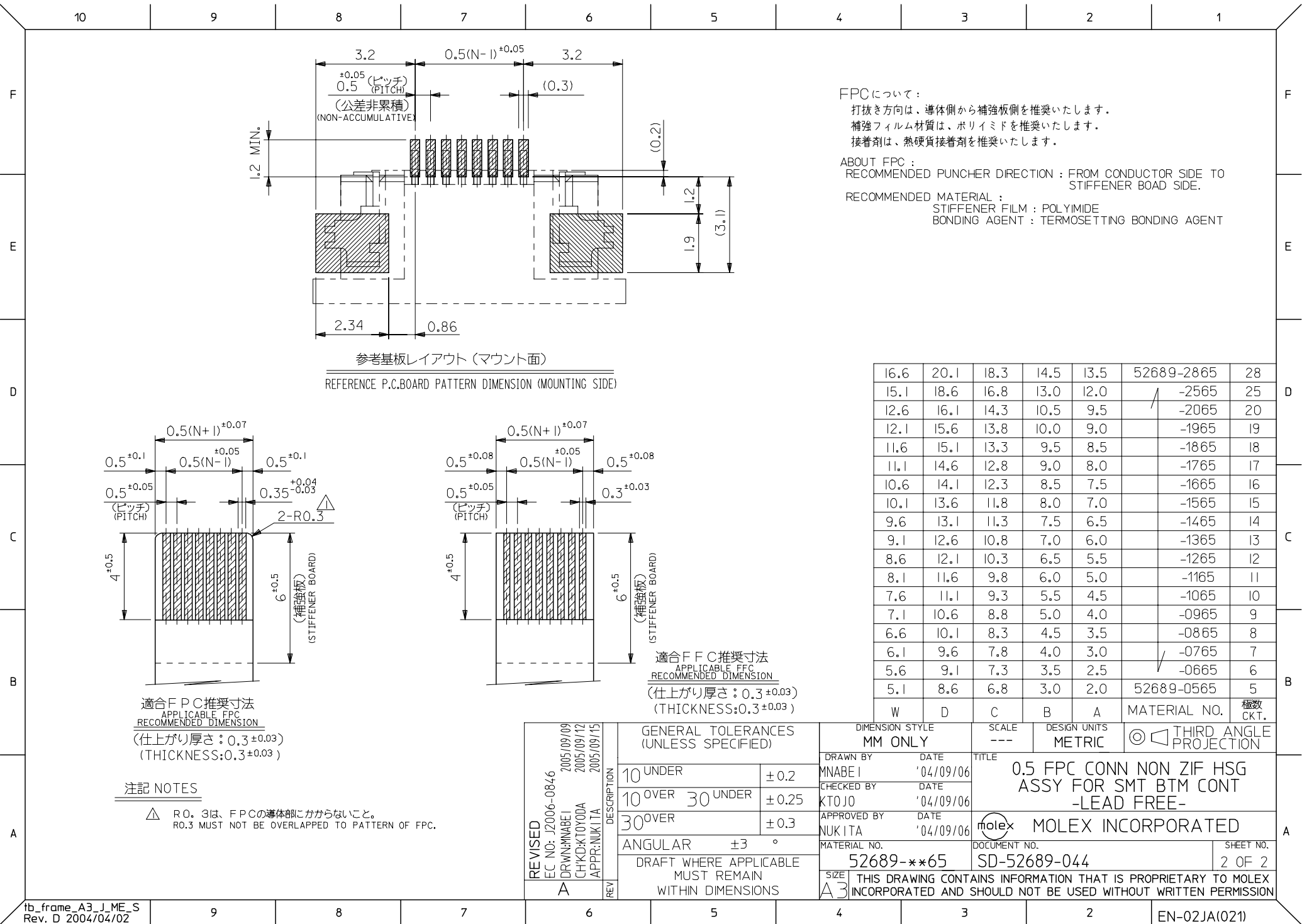
4. 各接点位置の上下方向のバラツキは 0.03MAX.

5. テール及び金具の平坦度は 0.1 以下。(TAIL & NAIL COPLANARITY TO BE 0.1 MAX.)

6. 本製品は 52689-xx70 の鉛フリー（部分全メッキ）品である。
THIS PRODUCT IS LEAD FREE OF 52689-xx70 (SELECTIVE GOLD).

THIS PRODUCT IS LEAD FREE OF 52689-xx70 (SELECTIVE GOLD).

REVISED	EC NO: J2006-0846 DRAWN: MNABE1 CHKD: KATOYODA APPR: NUKITA	2005/09/09 2005/09/12 2005/09/12	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
				10 UNDER	± 0.2	DRAWN BY MNABE1	DATE '04/09/06	TITLE 0.5 FPC CONN NON ZIF HSG ASSY FOR SMT BTM CONT -LEAD FREE-			
				10 OVER 30 UNDER	± 0.25	CHECKED BY KTOJO	DATE '04/09/06				
				30 OVER	± 0.3	APPROVED BY NUKITA	DATE '04/09/06	 MOLEX INCORPORATED			
				ANGULAR ±3 °		MATERIAL NO. 52689-**65					
				DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							
A	REV			SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						



F

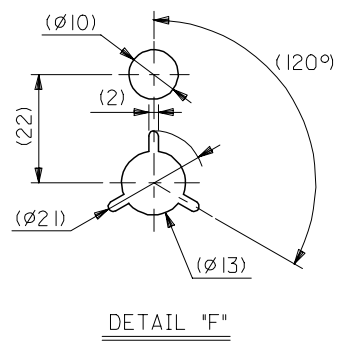
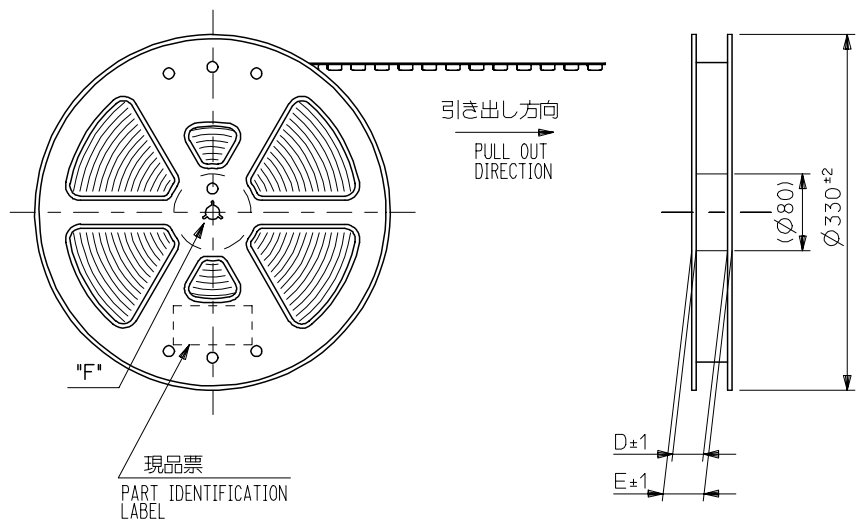
E

D

C

B

A



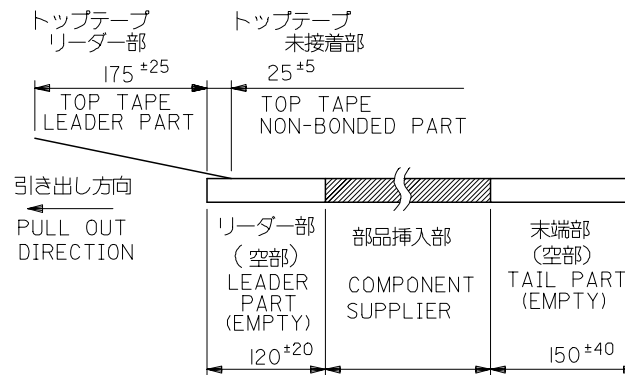
5. 材料
- キャリアテープ:ポリプロピレン (PP)
トップテープ:PET, PE, PEF
リール:ポリスチレン (PS) <リサイクル材を含む>

MATERIAL CARRIER TAPE:POLYPROPYLENE
TOP TAPE:PET,PE,PEF
REEL:POLYSTYRENE(PS)
<RECYCLE MATERIAL CONTAINED>

6. 本製品は 52689-**96 の鉛フリー (部分金メッキ) 品である。
THIS PRODUCT IS LEAD FREE OF 52689-**96 (SELECTIVE GOLD).

注記 NOTES

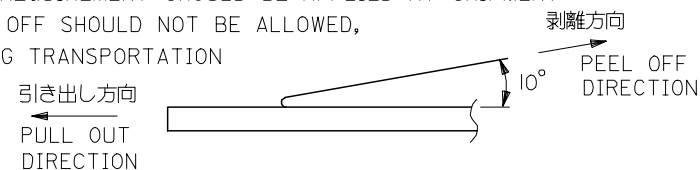
- 製品詳細寸法については図面 SD-52689-044 を参照下さい。
RE DETAILED DIMENSION,SEE SD-52689-044
- 梱包数量:1000個/リール
NUMBER OF CONNECTORS:1000PCS/REEL
- リードテープ長さ LEAD TAPE LENGTH



- トップテープの剥離強度: (剥離方向は下図参照)
0.1~1.3N (10~130gf) 尚、本規格値は、出荷時に適用。

(但し、輸送時に剥離が発生しない事。)

PEELING OFF FORCE OF TOP TAPE
0.1~1.3N (10~130gf) (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.)
THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT
PEEL OFF SHOULD NOT BE ALLOWED,
DURING TRANSPORTATION



REV	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY	DATE	TITLE	METRIC		
0	RELEASED EC NO: J2005-0419 DRWN:MNABE1 2004/09/07 CHKD:KTOJO 2004/09/08 APPR:NUKITA 2004/09/14	10 OVER 30 UNDER	±0.25	CHECKED BY	DATE	0.5 FPC CONN NON ZIF UPPER CONT EMBSTP PKG -LEAD FREE-	moLEX	MOLEX INCORPORATED	
		30 OVER	±0.3	APPROVED BY	DATE				
		ANGULAR	±3 °	MATERIAL NO.	DATE	52689-**74	DOCUMENT NO.	SD-52689-045	SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION				1 OF 2	

